



Material Content Data Sheet



Sales Product Name		BTS7008-2EPA		Issued		4. July 2019		
MA#		MA001949434						
Package		PG-TSDSO-14-22		Weight*		65.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.479	2.26	2.26	22603	22603
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.038	0.06		576	
	non noble metal	iron	7439-89-6	0.754	1.15		11527	
wire	non noble metal	copper	7440-50-8	30.617	46.81	48.03	468050	480297
	non noble metal	copper	7440-50-8	0.924	1.41	1.41	14133	14133
	encapsulation	organic material	carbon black	1333-86-4	0.086	0.13		1314
encapsulation	plastics	epoxy resin	-	3.353	5.13		51260	
	inorganic material	silicondioxide	60676-86-0	25.220	38.55	43.81	385547	438121
	leadfinish	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25096
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12475	12475
glue	plastics	epoxy resin	-	0.083	0.13		1273	
	noble metal	silver	7440-22-4	0.393	0.60	0.73	6002	7275
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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